# ■ MN1021617

Туре	MN1021617						
ROM (x8-bit)	128 K						
RAM (×8-bit)	4 K						
Package	LQFP128-P-1818C *Lead-free, FLGA165-C-1111 *Lead-free						
Minimum Instruction Execution Time	With main clock operated 50 ns (at 3.0 V to 3.6 V, 40 MHz) 100 ns (at 2.0 V to 3.6 V, 20 MHz)						
Interrupts	• RST pin • Watchdog • NMI pin • Timer counter 4 to 15 • Timer counter 16, 17, 21  • Timer counter 16 to 20 compare capture A • Timer counter 16 to 20 compare capture B  • Timer counter 21 capture A • Timer counter 21 capture B • Timer counter 21 capture D  • Timer counter 21 compare E • Timer counter 21 compare F • ATC ch.0 to 3 transfer finish  • External 0 to 7 • Serial ch.0 to 3 transmission • Serial ch.0 to 3 reception • KI pin (OR)  • A/D conversion finish						
Timer Counter	Timer counter 0: 8-bit × 1 (prescalers)  Clock source						
	Clock source						
• 0	Timer counter 4:8-bit × 1 (timer output, A/D conversion start up)  Clock source						
	Interrupt source						
	Clock source						
	timer counter 1 output Interrupt source ············ underflow of timer counter 8						
	Timer counter 12: 8-bit × 1 (timer output)  Clock source						
	Timer counter 13: 8-bit × 1 (timer output)  Clock source						
	Timer counter 14: 8-bit × 1 (timer output)  Clock source						
	Interrupt source underflow of timer counter 14  Panasonic MAE00006D						

1 Panasonic MAE00006DEM

Timer Counter (Conti	nue) Time	cr counter 15 : 8-bit × 1 (timer output)  Clock source						
		output  Interrupt sourceunderflow of timer counter 15						
	Coni	(Connectable) timer counter 0 to 3, 4 to 7, 8 to 11, 12 to 15						
		er counter 16, 17 : 16-bit × 1						
	(tir	ner output, event count, input capture, output compare, PWM output, 2-phase encorder input)  Clock source						
		Interrupt sourcecoincidence with compare capture A or at capture; coincidence with compare capture B or at capture; underflow of timer counter 16, 17						
		Timer counter 18: 16-bit × 1						
	(tii	ner output, event count, input capture, output compare, PWM output, 2-phase encorder input)  Clock source						
		Interrupt source coincidence with compare capture A or at capture; coincidence with compare capture B or at capture;						
		underflow of timer counter 18, 19, 20						
		er counter 19, 20: 16-bit × 1						
	(th	(timer output, event count, input capture, output compare, PWM output, 2-phase encorder input)  Clock source						
		Interrupt source coincidence with compare capture A of at capture;						
	* 1	coincidence with compare capture B or at capture; underflow of timer counter 18, 19, 20						
	T.							
	Time	r counter 21 : 24-bit × 1 (servo control)  Clock source						
		Interrupt source						
		when capturing to capture B;						
	<b>&gt;</b>	when capturing to capture D; when coinciding to compare E;						
		when coinciding to compare E;						
Serial Interface	Seria	10, 1:8-bit × 1 (transfer direction of MSB / LSB selectable, transmission / reception of 7, 8-bit length)  Clock source						
		al 2, 3, 8-bit × 1 (transfer direction of MSB / LSB selectable, transmission / reception of 7, 8-bit length)  Clock source						
		$UART \times 4$ (common use with serial 0 to 3)						
_	I <sup>2</sup> C >	I <sup>2</sup> C × 2 (common use with serial 1, 3; single master)						
I/O Pins I/O	100	• Common use : 56 (address data separate 8-bit mode) • Common use : 73 (address data multiplex 8-bit Mode)						
Input	'	• Common use : 8						
A/D Inputs		10-bit × 12-ch. (maximum input is 16) (with S/H)						
PWM	16-b	it × 5-ch. (timer counter 16 to 20)						
ICR	16-b	$16$ -bit $\times$ 5-ch., 24-bit $\times$ 1-ch. (timer counter 16 to 21)						
OCR	16-b	it $\times$ 5-ch., 24-bit $\times$ 1-ch. (timer counter 16 to 21)						
Notes		ress / data multiplex bus Interface, address / data separate bus interface, / 16-bit bus width selectable						

#### **Electrical Characteristics**

#### Supply current

Parameter	Symbol	Condition		Unit			
rarameter	Symbol	Condition	min	typ	max	Oilit	
Operating cumply current	IDDopr	VI = VDD or VSS, output open				50	mA
Operating supply current	Проорг	f = 40 MHz , VDD = 3.3 V					
Supply current at STOP	IDDS	Pin with pull-up resistor is open			50		
Supply culterit at STOP	IDDS	all other input pins and Hi-Z state input/output			30	μΑ	
Supply current at HALT	IDDH	pins are simultaneously applied VDD or VSS level				25	mA
Supply cultent at TALI	ПООП	f = 40  MHz, $VDD = 3.3  V$ , output open				23	IIIA

 $(Ta = -20^{\circ}C \text{ to } +70^{\circ}C, VDD = AVDD = 3.3 \text{ V}, VSS = AVSS = 0 \text{ V})$ 

### Pin Assignment



LQFP128-P-1818C \*Lead-free

## Pin Assignment (Continue)



		PB5,SBT3, SCL3	AVDD	P81,AN1	P83,AN3	P87,AN7	AVDD	P94,AN12, TM110	AVDD	P50,/WEL		
N.D.	N.D.										N.D.	N.D.
		PB3,SBI3	VSS	VREFL	P85,AN5	PD5,RTP5	P93,AN11	P96,AN14,	PC6,NBREQ	P52,/RE		
								TM15O				
N.D.	N.D.										N.D.	N.D.
VSS	PB2,SBT2, TM18IC	PB1,SBO2, TM17IC	PB4,SBO3, SDA3	P80,AN0	P84,AN4	AVSS	P91,AN9	P95,AN13, TM13O	PC7, NBRACK	P51,/WEH, /WE	VDD	P54,/RAS, /RFSH
PB0,SBI2,	PA4,SBO1,	PA5,SBT1,	VDD	AVSS	P86,AN6	P90,AN8	P92,AN10	P97,AN15	VSS	P53,/CS2.	P56,/CS3,	VDD
TM16IC	SDA1	SCL1								ALE	/UCAS, BIBT2	
PA1,SBO0	PA3,SBI1	PA0,SBI0	PA2,SBT0	AVSS	P82,AN2	PD4,RTP4	VREFH	P55,/CAS, /LCAS, BIBT1	VPP	P20,A0,/KI0	P21,A1,/KI1	P23,A3,/KI3
P75.	P73.	P77.	P72, TM17OA	P74. TM18OA				P22,A2,/KI2	P26,A6,/K16	P24,A4,/KI4	P27,A7,/KI7,	P25,A5,/KI5
TM18IOB, TM21ID	TM17OB, STOP	TM20IOA	172, 13117011	171, 11110011	N.D.	N.D.	N.D.	25,12,7112	1 20,110,7,110		TMI17B	1 25,125,113
P71,	PD3,RTP3	VDD	VDD	PD2,RTP2	11.25	T.D.		P30,A8	PD7,RTP7	VPP	P31,A9	PD6,RTP6
TM16OB, WDOUT					N.D.	N.D.	N.D.		V. R.		4	<b>\</b> ·
P65,IRQ5,TM 18IA	P67,IRQ7,/EX TDK	P66,IRQ6	P70,TM16OA	P64,IRQ4, TM17IA	N.D.	N.D.	N.D.	P34,A12	P32,A10	P33,A11	P35,A13	PC4,TM12O, TM8I, TM21IA
P63,IRQ3, TM16IB	P61,IRQ1, TM3I	P62,IRQ2, TM16IA	VDD	P60,IRQ0	MODE0	PD0,RTP0	P05,AD5,D5	P03,AD3,D3	P36,A14	VPP	P41,A17	P37,A15
VSS	P76, TM19IOA	PC0,TM4O, TM10I	VDD	PC2,TM8O, TM6I	P15,AD13, D13	P13,AD11, D11	P11,AD9,D9	VSS	P01,AD1,D1	P42,A18	P40,A16	VDD
/RST	P57,/DUMX, BOSC	PC5,NMI	OSCO	MODE2	P14,AD12, D12	VSS	P07,AD7,D7	VSS	P47,A23, /CS1	P44,A20	P45,A21	P43,A19
N.D.	N.D.	VSS	PC1,TM6O, TM11I	PC3,TM10O, TM7I, TM21IR	P16,AD14, D14	PD1,RTP1	P10,AD8,D8	VDD	P02,AD2,D2	P46,A22, /CS0	N.D.	N.D.
		OSCI	VSS	MODE1	P17,AD15,D1	P12,AD10, D10	P06,AD6,D6	P04,AD4,D4	VDD	P00,AD0,D0		
N.D. 13	N.D. 12	11	10					5	$\sim$		N.D.	

FLGA165-C-1111 \*Lead-free

The MN102F1617 is manufactured and sold under license agreement with BULL CR8 Inc. Note that MN102F1617 cannot be used as the IC card.

- \* A1 has no electrode (pin).
- \* N.D. (not defined) has an electrode (pin) but not guaranteed for N.C. (not connected). Pay sufficient attention so as not to cause shorting with any other wiring on the user board.
- \* VPP, VDD, VSS, AVDD and AVSS has multiple electrodes (pins). Electrodes having the same name are shorted internally.

#### **Support Tool**

In-circuit Emulator	PX-ICE102H1617-LQFP128-P-1818C	Not applicable to FLGA165-C-1111.				
	Minimum instruction execution time	57.1 ns (at 35 MHz)				
Flash Memory Built-in Type	Туре	MN102F1617				
	ROM (× 8-bit)	128 K				
	RAM (× 8-bit)	4 K				
	Minimum instruction execution time	62.5 ns (at 3.0 V to 3.6 V, 32 MHz)				
		83.3 ns (at 2.7 V to 3.6 V, 24 MHz)				
	Package	LQFP128-P-1818C *Lead-free, FLGA165-C-1111 *Lead-free				

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